MMBTA56WT1

Driver Transistor

PNP Silicon

Features

• Moisture Sensitivity Level: 1

• ESD Rating: Human Body Model – 4 kV Machine Model – 400 V

• Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	-80	Vdc
Collector-Base Voltage	V _{CBO}	-80	Vdc
Emitter-Base Voltage	V _{EBO}	-4.0	Vdc
Collector Current – Continuous	I _C	-500	mAdc

THERMAL CHARACTERISTICS

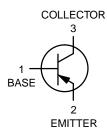
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board T _A = 25°C	P _D	150	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	833	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

http://onsemi.com





SC-70 (SOT-323) CASE 419 STYLE 3

MARKING DIAGRAM



FM = Device Code
M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

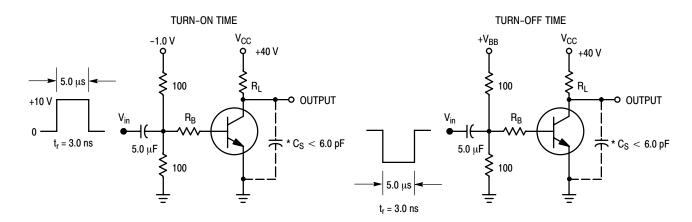
ORDERING INFORMATION

Device	Package	Shipping [†]
MMBTA56WT1	SC-70	3000/Tape & Reel
MMBTA56WT1G	SC-70 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	'			
Collector–Emitter Breakdown Voltage (Note 1) (I _C = -1.0 mAdc, I _B = 0)	V _(BR) CEO	-80	_	Vdc
Emitter–Base Breakdown Voltage ($I_E = -100 \mu Adc, I_C = 0$)	V _{(BR)EBO}	-4.0	_	Vdc
Collector Cutoff Current $(V_{CE} = -60 \text{ Vdc}, I_B = 0)$	I _{CES}	-	-0.1	μAdc
Collector Cutoff Current $(V_{CB} = -60 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -80 \text{ Vdc}, I_E = 0)$	Ісво	- -	_ _0.1	μAdc
ON CHARACTERISTICS		•	•	
DC Current Gain $ \begin{aligned} \text{(I}_{\text{C}} &= -10 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} &= -100 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \end{aligned} $	h _{FE}	100 100	_ _	-
Collector–Emitter Saturation Voltage (I _C = –100 mAdc, I _B = –10 mAdc)	V _{CE(sat)}	-	-0.25	Vdc
Base-Emitter On Voltage (I _C = -100 mAdc, V _{CE} = -1.0 Vdc)	V _{BE(on)}	_	-1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS	•	•	•	
Current-Gain - Bandwidth Product (Note 2) (I _C = -100 mAdc, V _{CE} = -1.0 Vdc, f = 100 MHz)	f _T	50	_	MHz



*Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
 f_T is defined as the frequency at which |h_{fe}| extrapolates to unity.

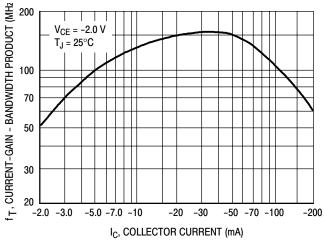


Figure 2. Current-Gain — Bandwidth Product

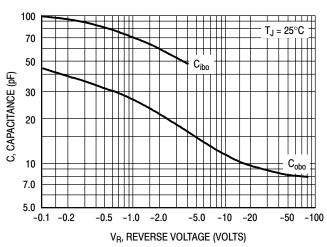


Figure 3. Capacitance

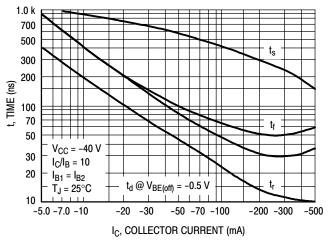


Figure 4. Switching Time

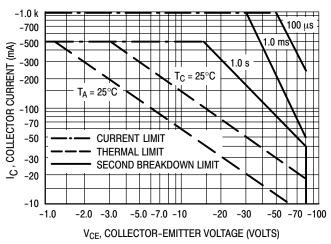


Figure 5. Active-Region Safe Operating Area

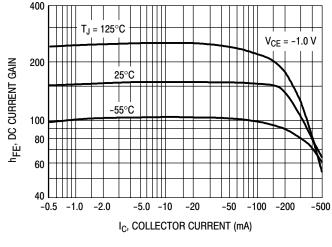


Figure 6. DC Current Gain

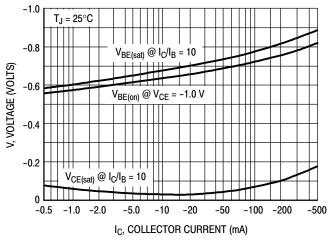
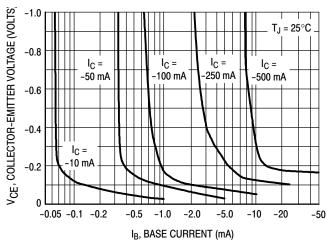


Figure 7. "ON" Voltages

MMBTA56WT1

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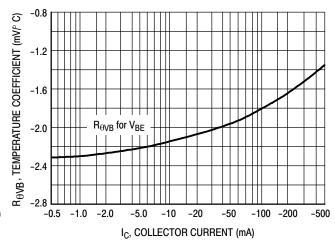
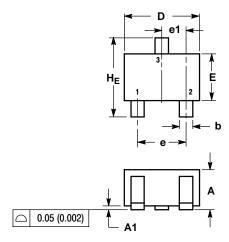


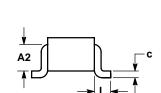
Figure 8. Collector Saturation Region

Figure 9. Base–Emitter Temperature Coefficient

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE M





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 MALEMATICAL TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: INCH.

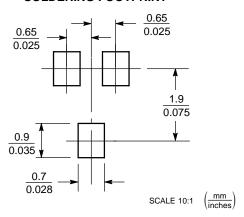
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF 0.028 REF					
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF				0.017 REF	
HE	2.00	2.10	2.40	0.079	0.083	0.095

STYLE 3:

PIN 1. BASE 2. EMITTER

2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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